

FIRE Plasma Facing Component Design Studies

*NSO Engineering Peer Review Meeting
Princeton, NJ*

Jun 4-6, 2000

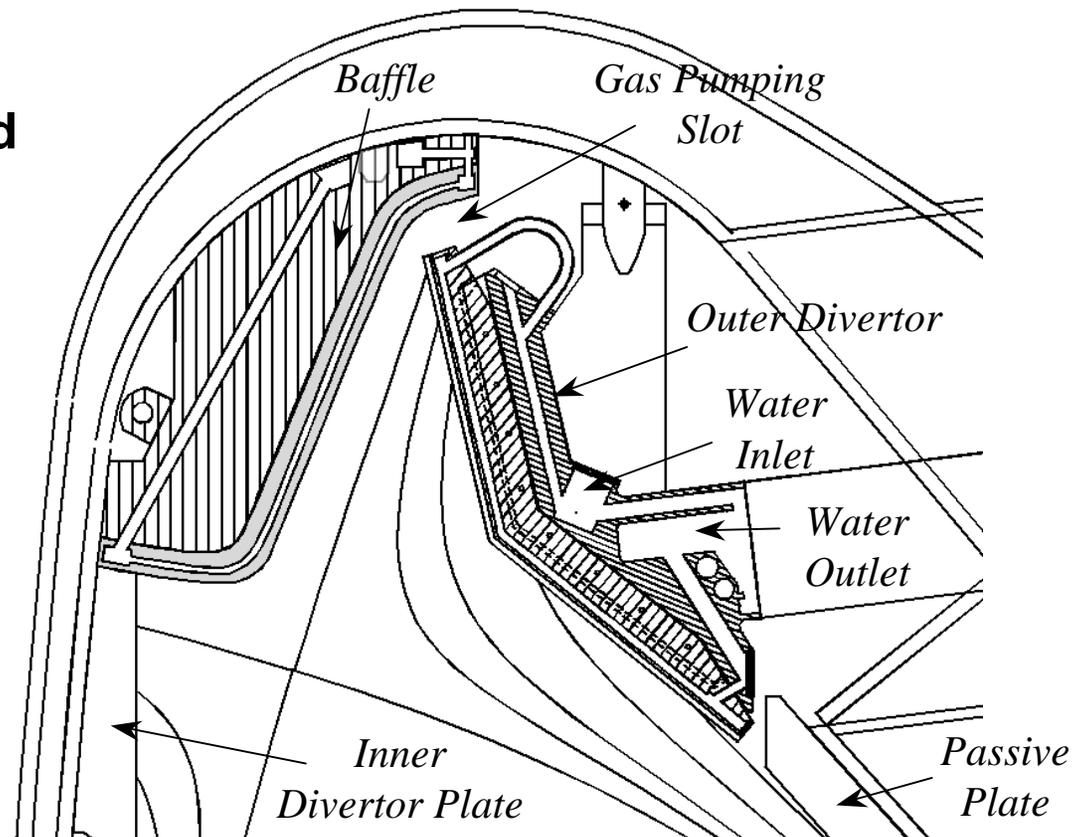
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Contributions from
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FIRE Divertor Components

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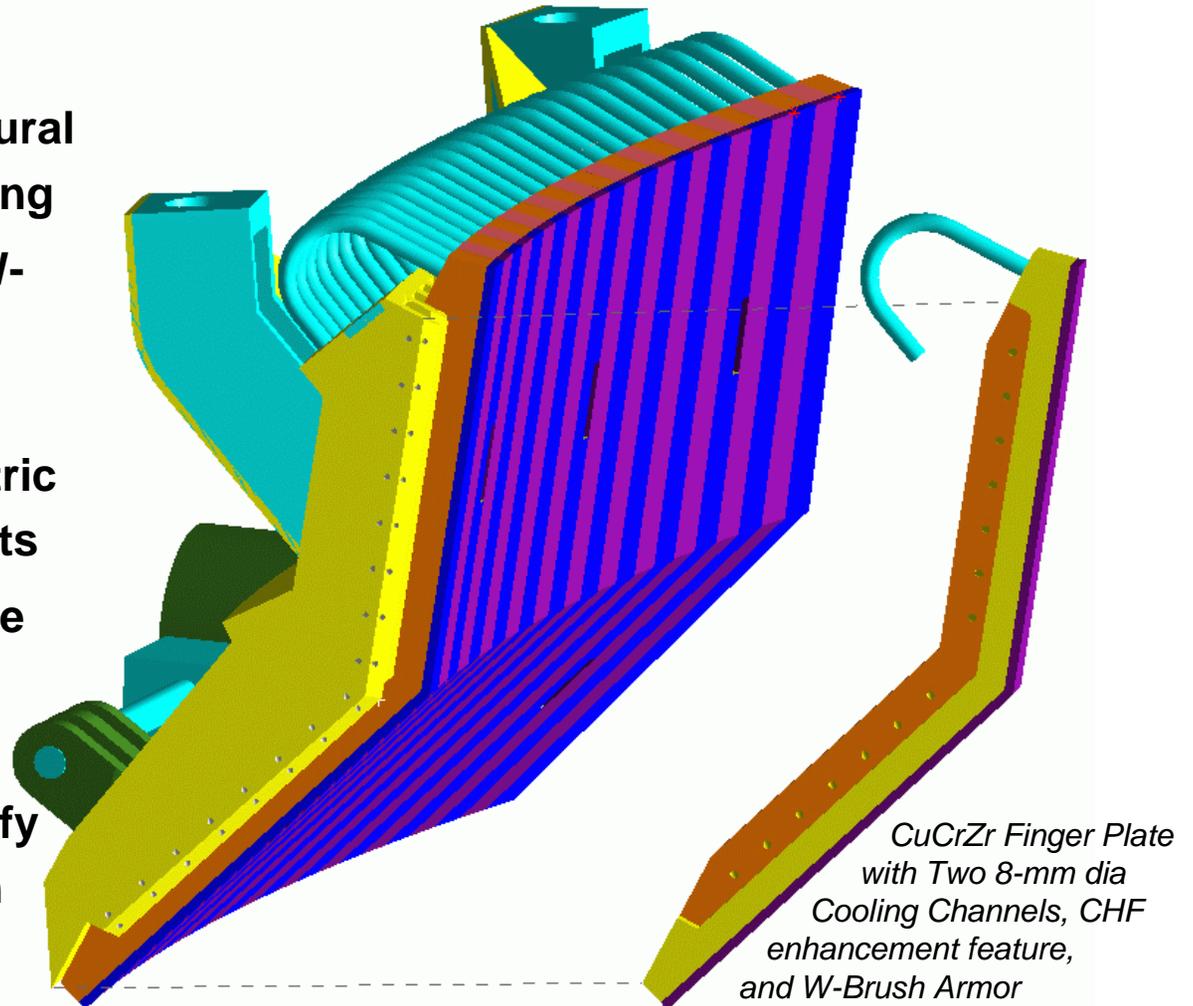
- ❑ Build on design/fabrication approaches developed during ITER-EDA
- ❑ W-brush armor for divertor and plasma-sprayed Be for first wall tiles
- ❑ Cu-alloy finger elements for high heat flux outer target
- ❑ Swirl tape or helical wire inserts for CHF enhancement
- ❑ Dome-like construction for lower heat flux baffle
- ❑ Passively-cooled W-Cu tiles for low heat flux inner target
- ❑ Modular units for remote maintenance during operation



Outer Divertor Design Concept

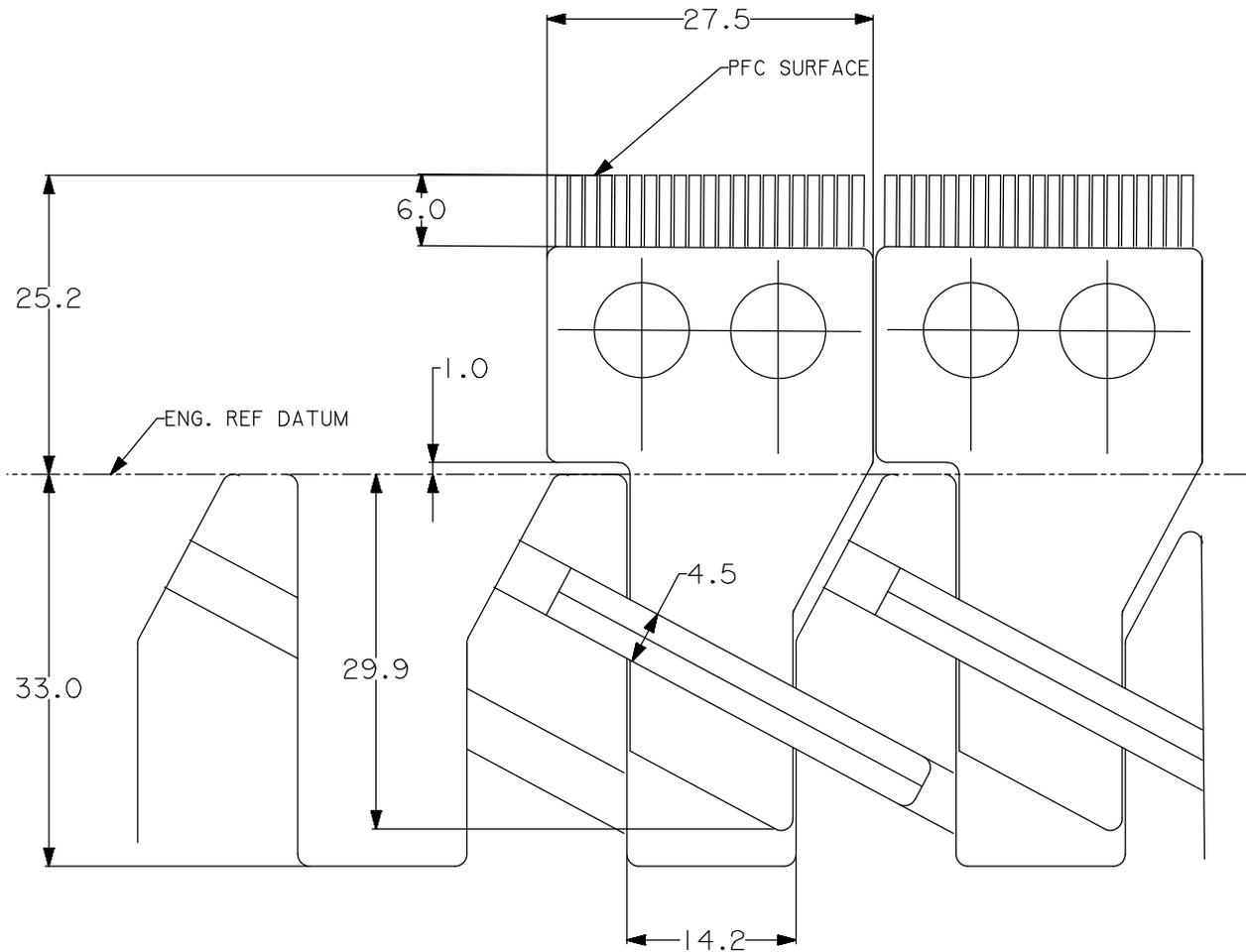
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- ❑ SS316LN back plate for structural support and coolant manifolding
- ❑ 24 CuCrZr finger plates with W-brush armor, attached to back plate using pressed pins
- ❑ Actively cooled using concentric pipe feed through divertor ports
- ❑ HIP-bond armor using separate canister welds around each finger plate
- ❑ HHF cycle finger plates to verify armor joint prior to integration



Finger Element Attachment Concept

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Component Cooling Assessment

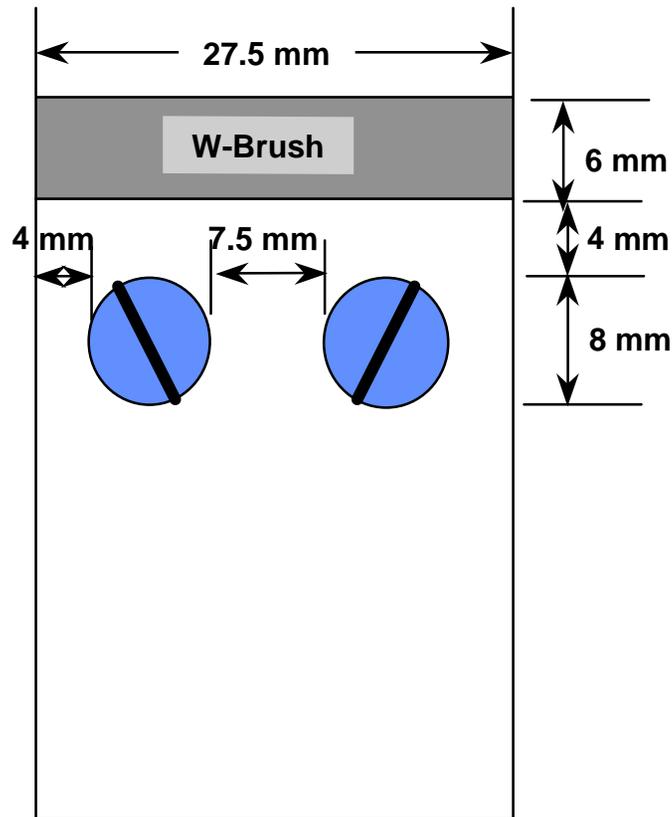
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Parameter	Outer Divertor	Baffle
Total Power (MW)	34.3	10.7
Peak Power/module (MW)	2.32	0.58
Peak Heat Flux (MW/m ²)	20.0	6.0
Nuclear heating in W (W/cm ³)	42	34
Nuclear heating in Cu (W/cm ³)	16	13
Channel Diameter (mm)	8	10
Pitch (mm)	14	21
Number per module	48	30
Number in series	2	2
Enhancement	ST, t=1.5 mm Y= 2	None
Maximum PFC Temp (C)	1585	738
Maximum Copper Temp (C)	488	404
Flow velocity (m/s)	10	3
Flow/module (liter/s)	9	3.5
Exit coolant Temperature (C)	95	73.3
Exit Pressure (MPa)	1.06	1.48
Exit Subcooling (C)	87	120
Critical Heat Flux (MW/m ²)	44.	12.1
Maximum Wall Heat Flux (MW/m ²)	30.6	6.31

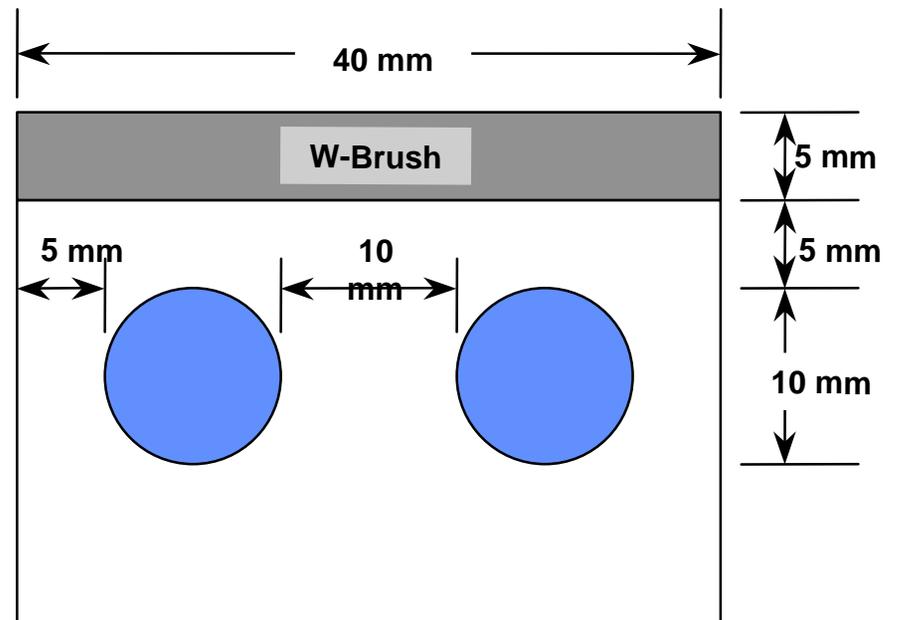
Unit Cell Geometry for Divertor and Baffle

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Divertor Unit Cell



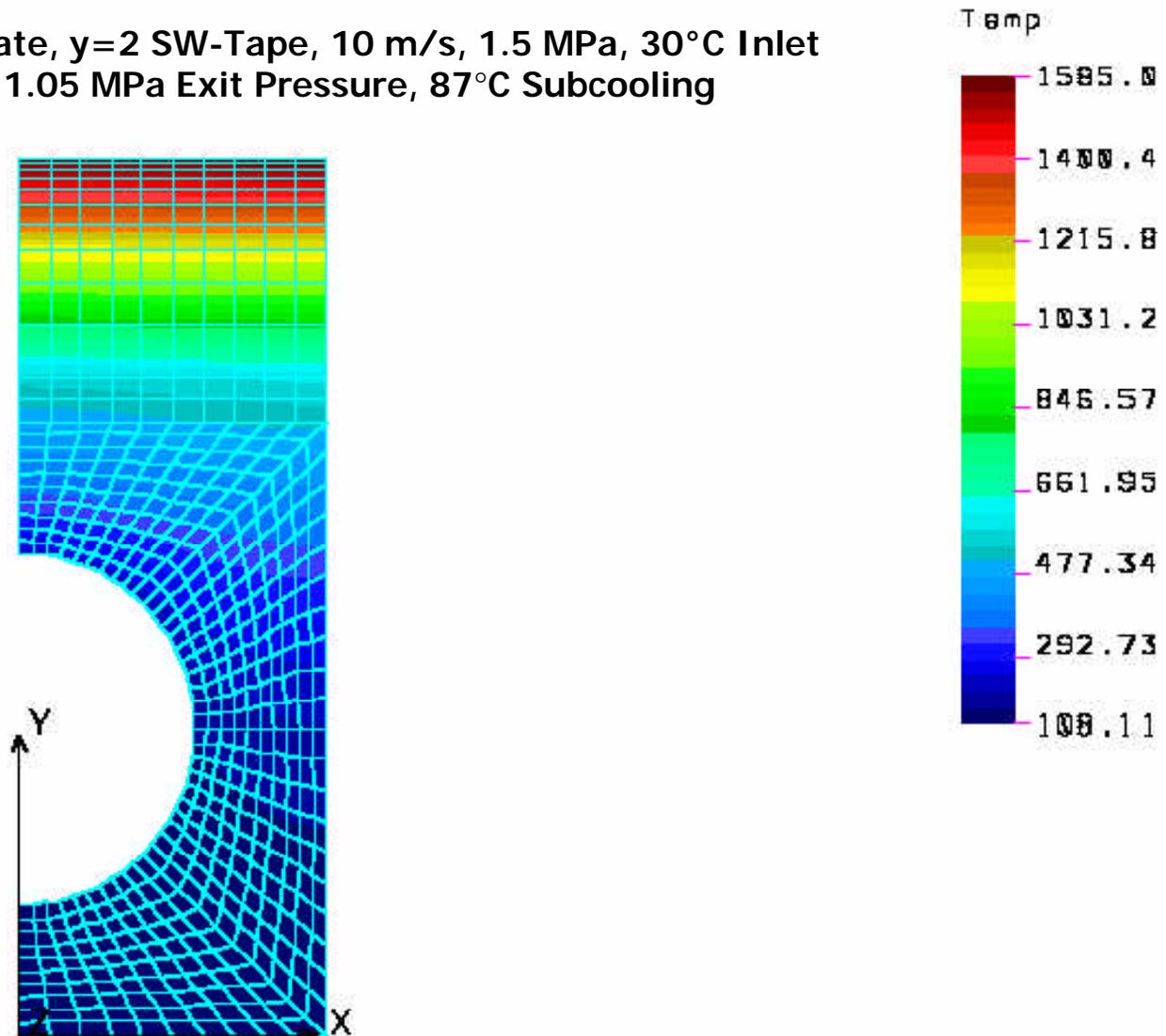
Baffle Unit Cell



Outer Divertor Temperature Distribution

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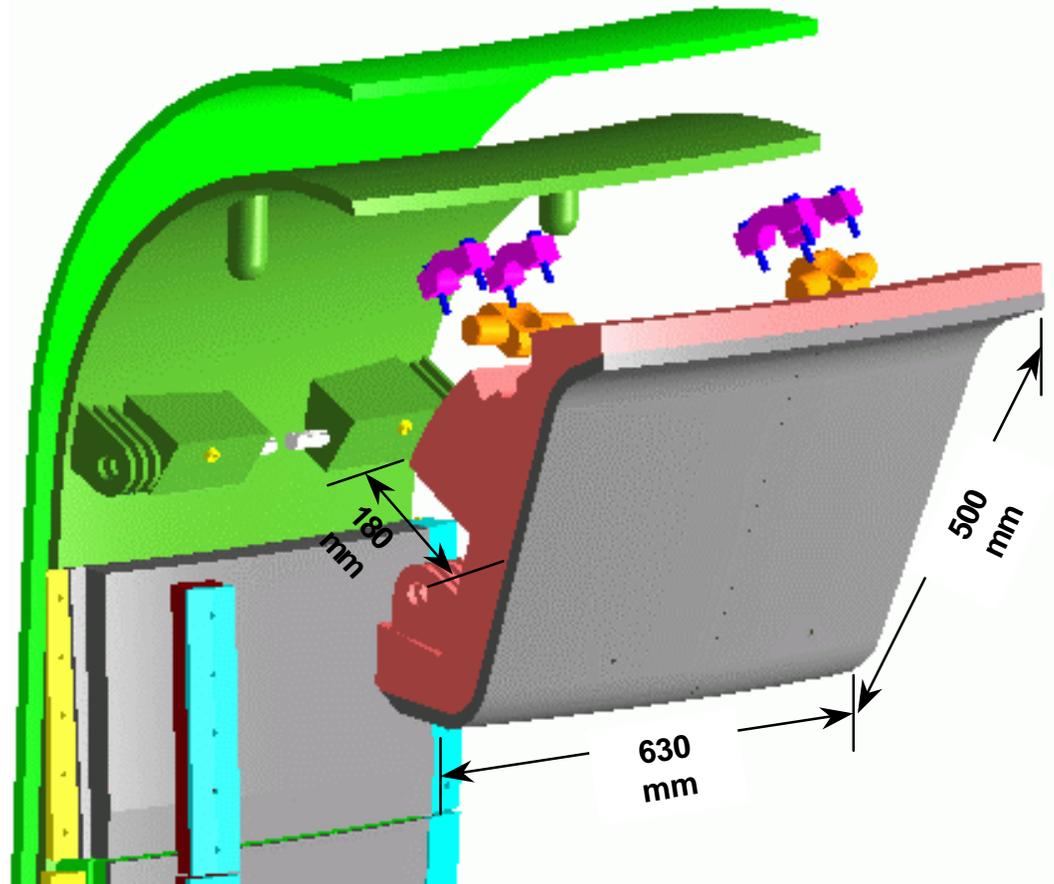
20 MW/m², Steady-State, y=2 SW-Tape, 10 m/s, 1.5 MPa, 30°C Inlet
95°C Exit Temp, 1.05 MPa Exit Pressure, 87°C Subcooling



Baffle Plate Design Concept

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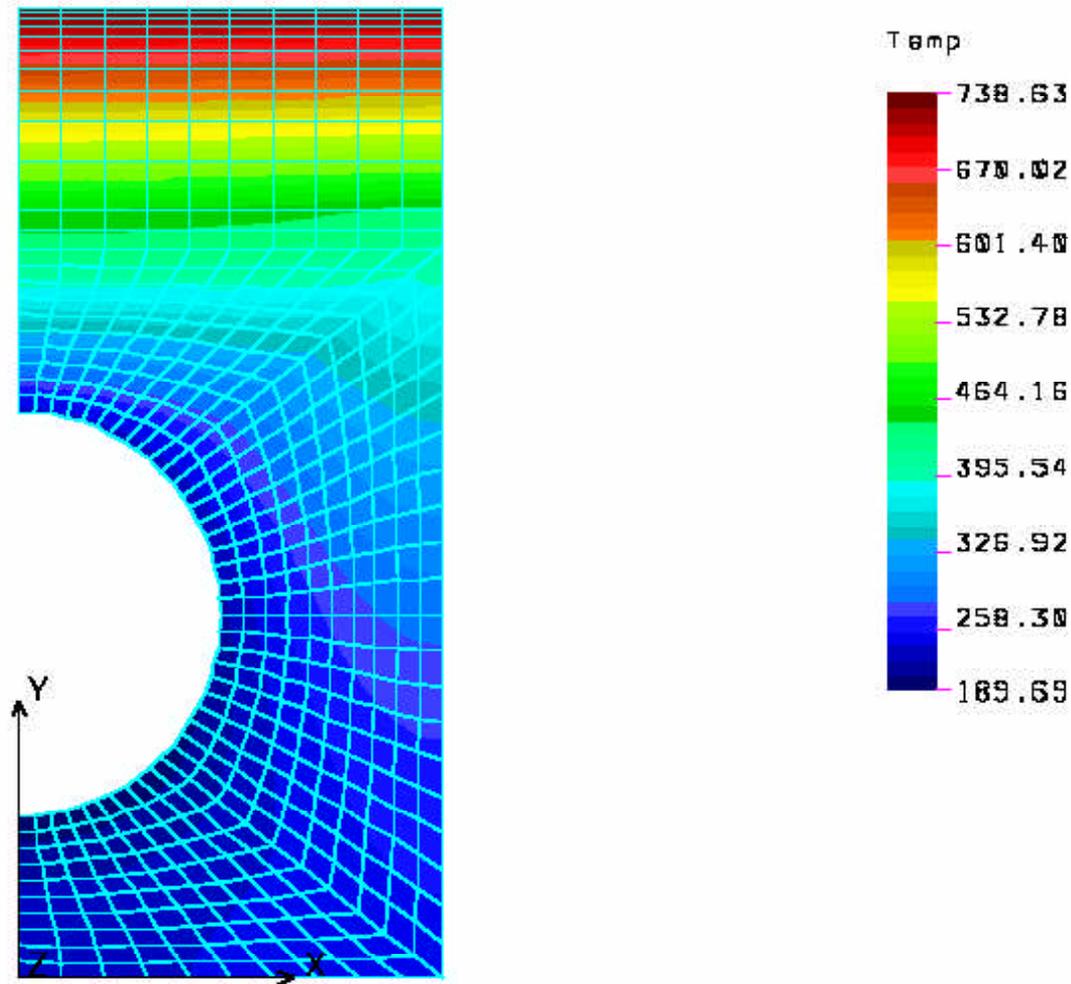
- ❑ Cooled CuCrZr forging with W-brush armor for erosion control
- ❑ Need to develop coolant supply/return concepts for heat removal
- ❑ Integration with outer divertor module looks feasible, flow rates are low (3.5 l/s)
- ❑ Attached to vessel using upper pins/rotating sockets and lower shear plates/pins
- ❑ HIP-bond armor over entire baffle surface using single perimeter e-beam weld



Baffle Temperature Distribution

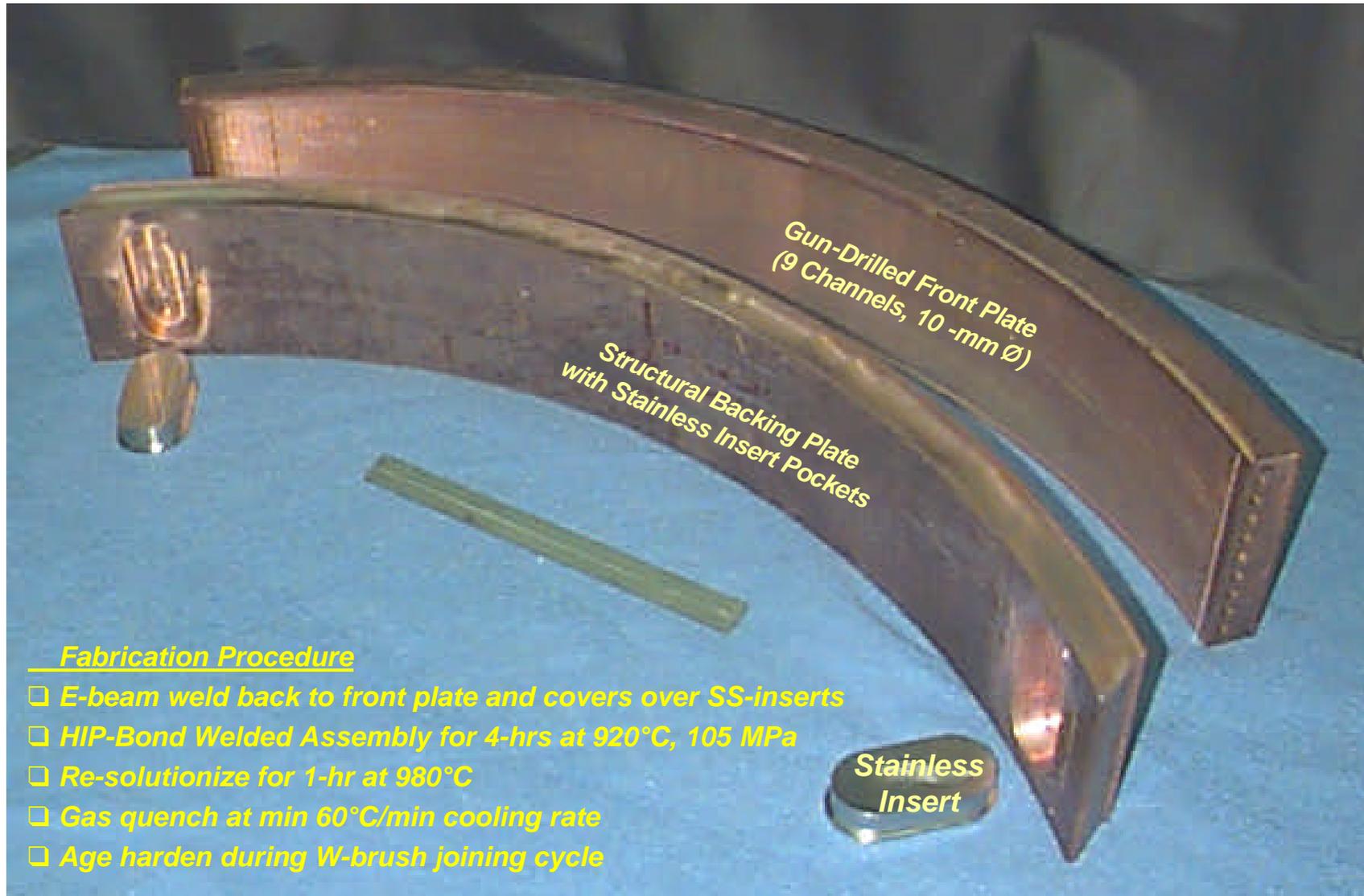
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6 MW/m², Steady-State, Smooth Channels, 3 m/s, 1.5 Mpa, 30°C Inlet
73°C Exit Temp, 1.48 MPa Exit Pressure, 120°C Subcooling



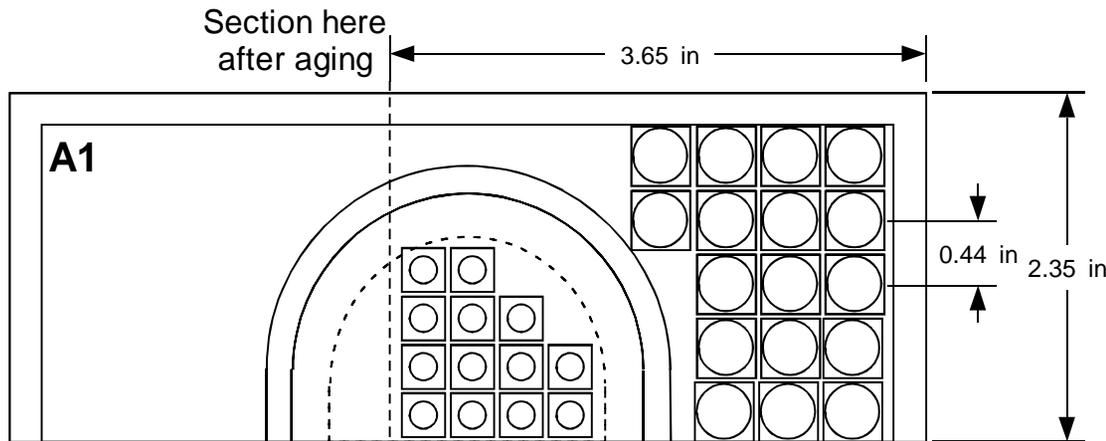
ITER Dome Part Demonstrated Baffle Fabrication Process

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Tensile Tests on Witness Part Bonds Confirmed Bond Quality

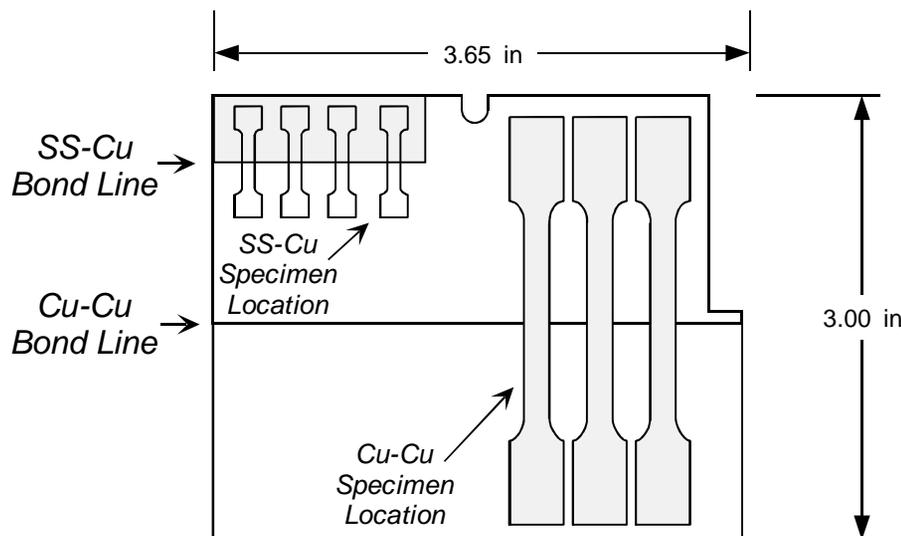
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Piece A1 Kept by Boeing for Metallography Specimens

Piece A Sent to WMT&R for Tensile Testing

- Machine specimens from both Cu-Cu and SS-Cu interfaces
 - Cu-Cu Tests performed at RT, 150, 300, 450°C
 - SS-Cu tests performed at RT, 150, 300°C
 - Specimens taken from age-hardened material



□ Summary of Cu-Cu Bonds

Temp	0.2%YS	%UE
RT	272	13.5
150	243	7.9
300	217	7.2
450	179	1.7

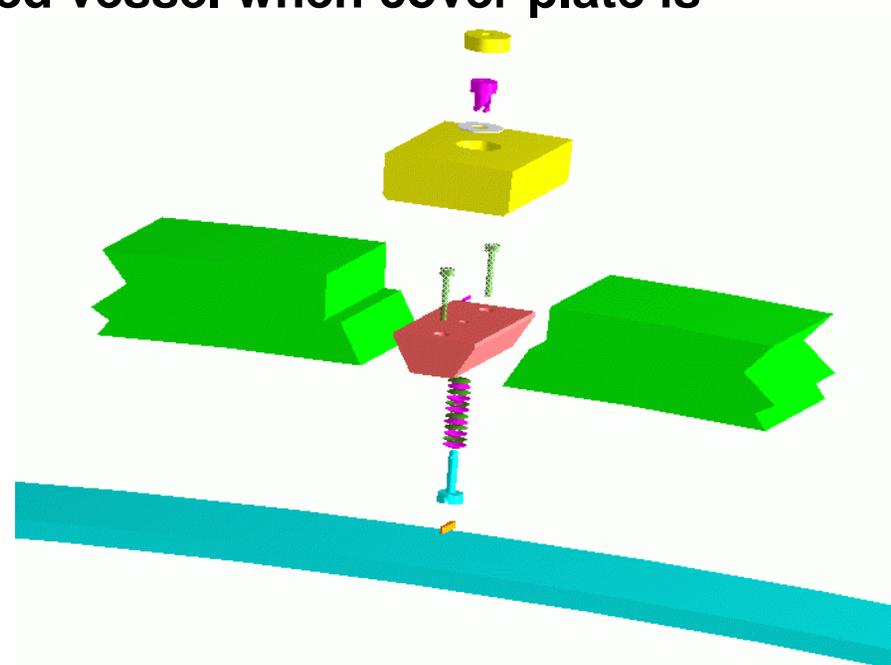
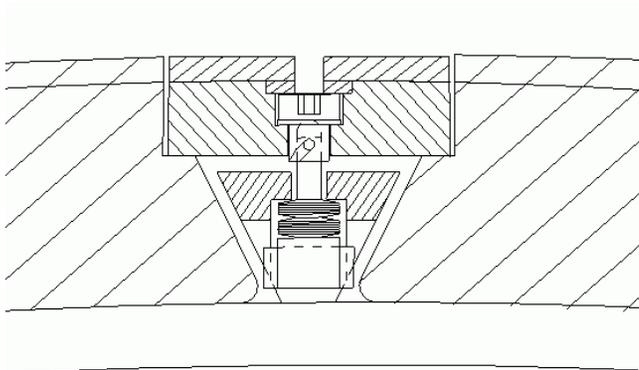
□ Summary of Cu-SS Bonds

Temp	0.2%YS	%UE
RT	278	10.0
150	247	9.8
300	223	5.9

First Wall/Inner Divertor Tile Mounting Concept

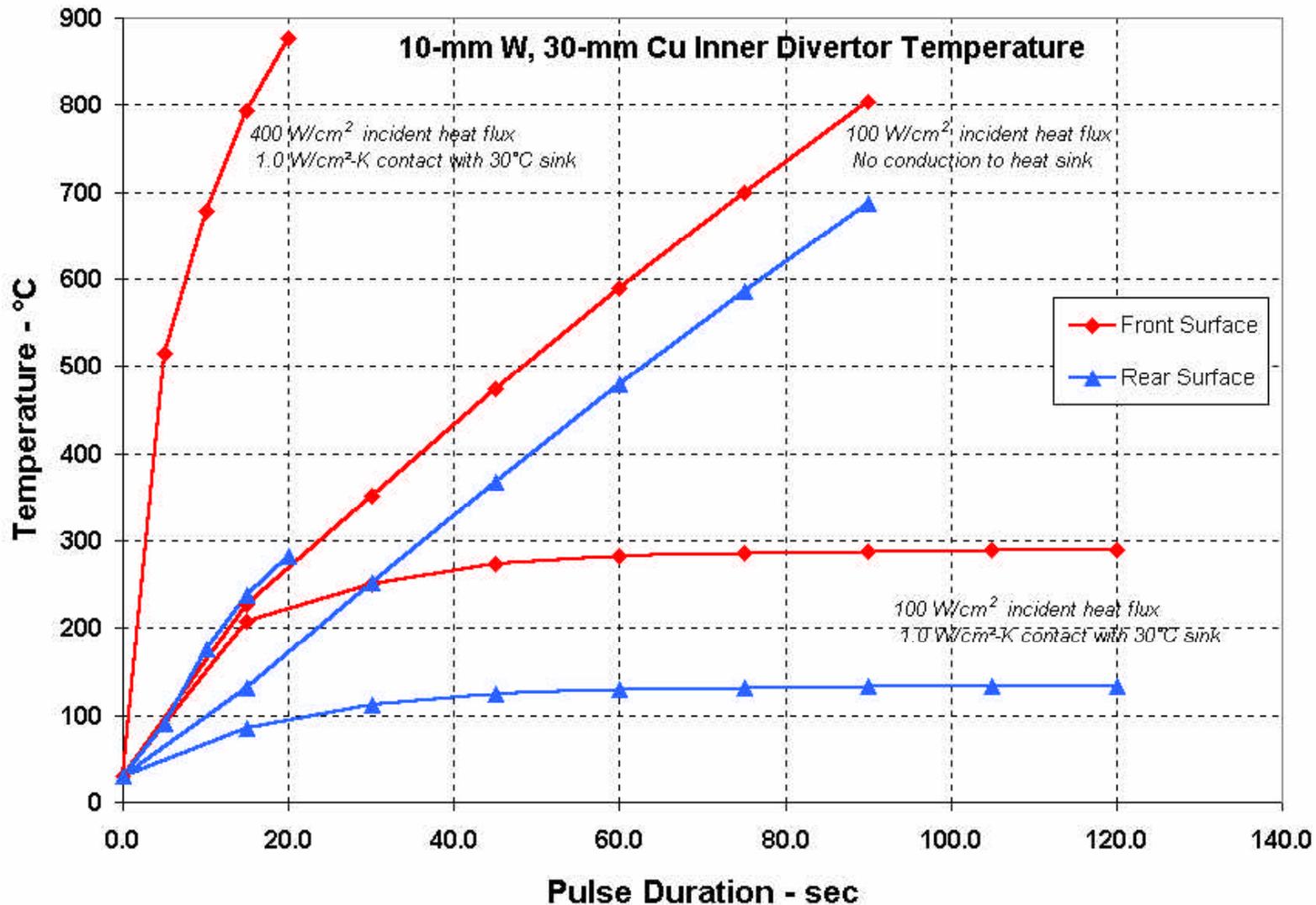
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- ❑ 30-mm thick CuCrZr plates with 5-mm thick tungsten or plasma-sprayed beryllium armor
- ❑ Wedge-shaped SS316LN rails bolted to vessel, provide mechanical support
- ❑ Rails include captive fastener hardware for loading thermal interface contacts with cooled vessel when cover plate is installed



Inner Divertor Temperature Assessment

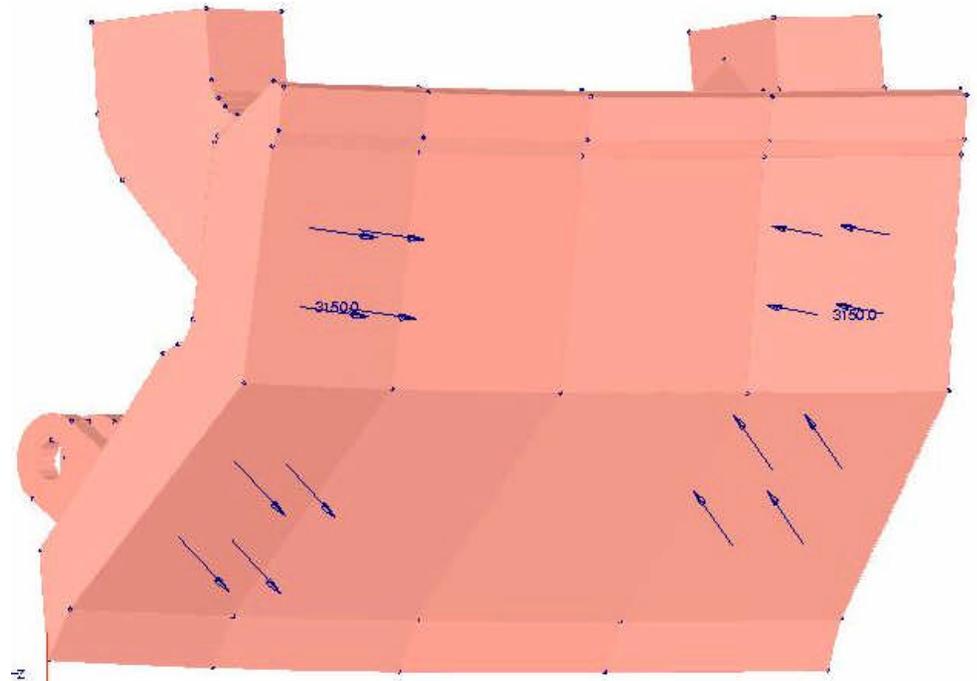
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Halo Current/Disruption Load Assessment

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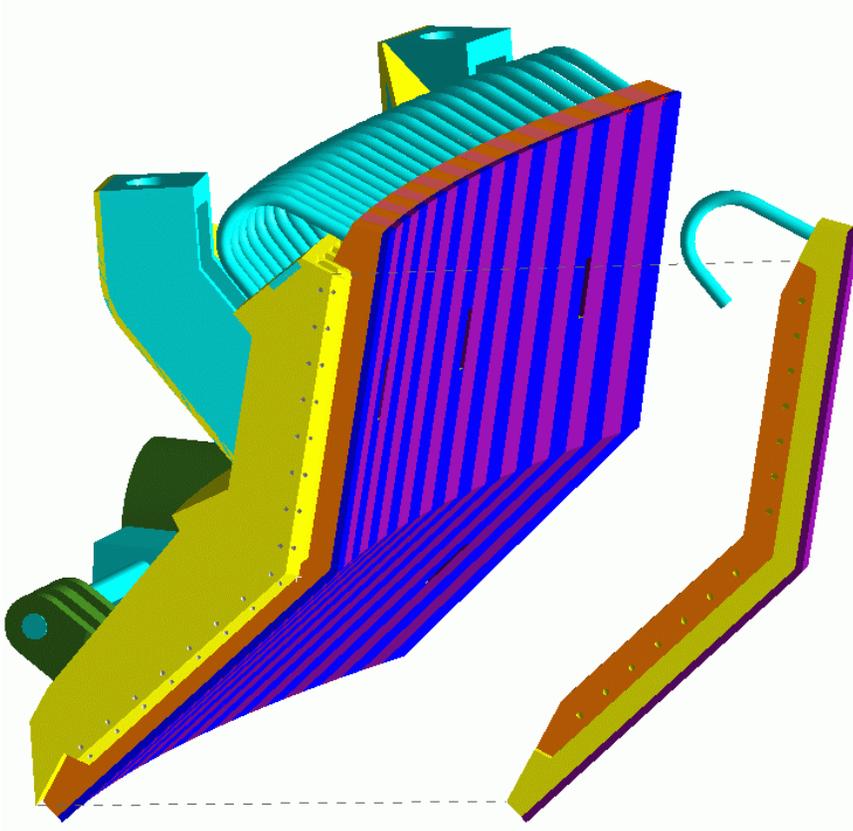
- ❑ 1.8 MN disruption loads applied as opposing 3150 lb/in² pressures over end quarter panels
- ❑ 0.8 MN halo current load applied as uniform 350 lb/in² pressure over entire plate surface
- ❑ Evaluate back plate response only, no credit taken for finger element load sharing
- ❑ Model pins as sliding contact interfaces fixed by springs to ground
- ❑ Include cross manifold channels in back plate and remove finger attach ribs from front surface



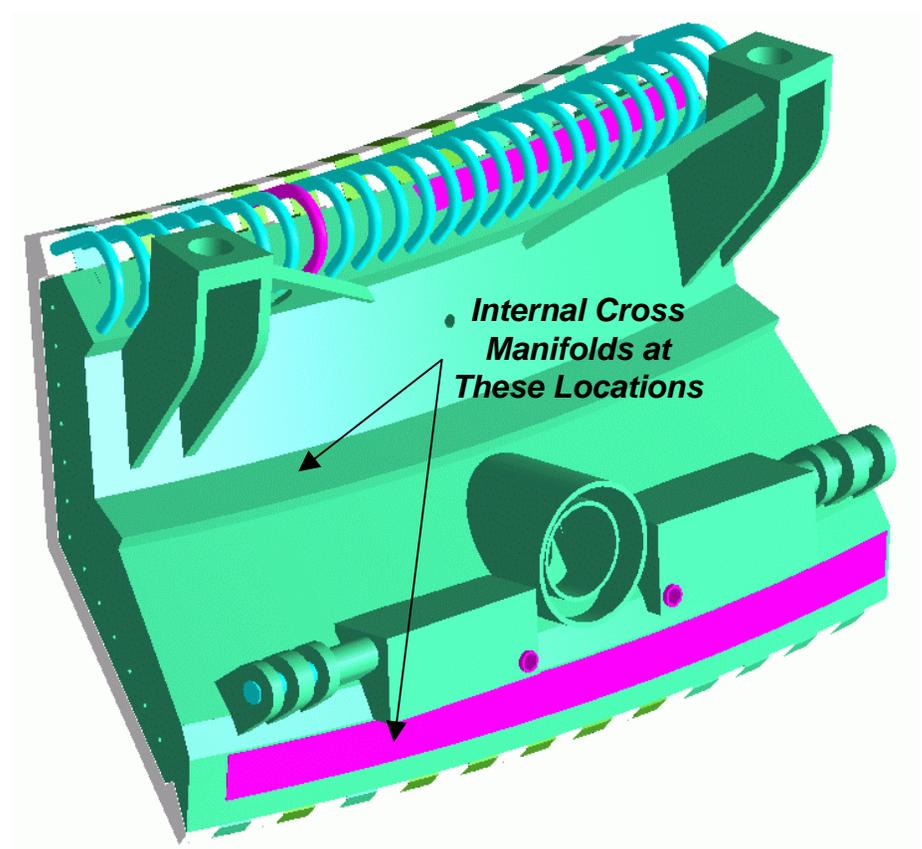
Initial Outer Divertor Configuration

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Front Surface View Showing
Finger Elements



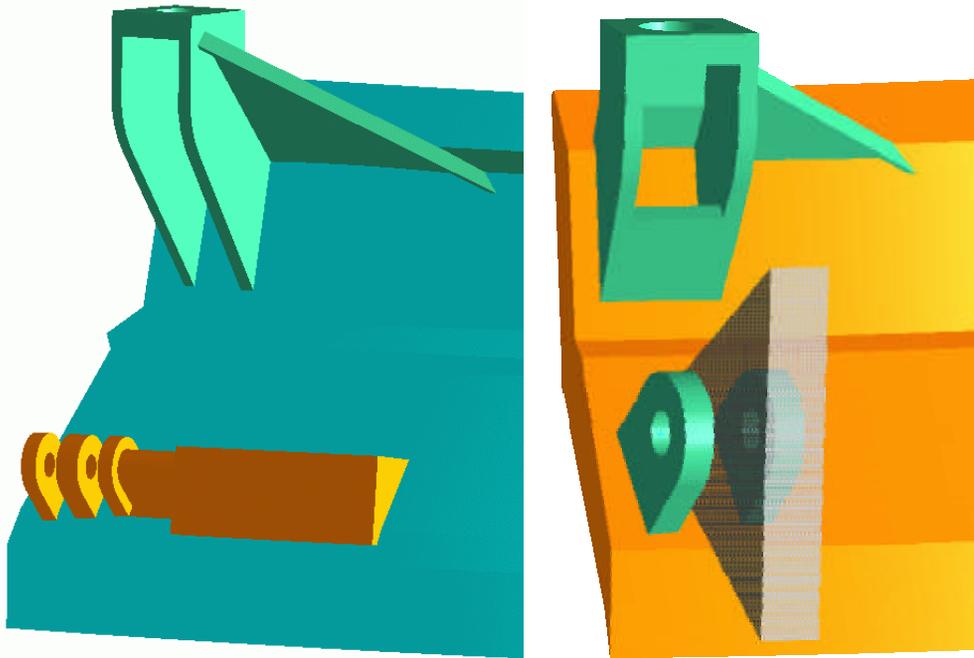
Rear Surface View Showing Vessel
Attachment / Cooling Interface Features



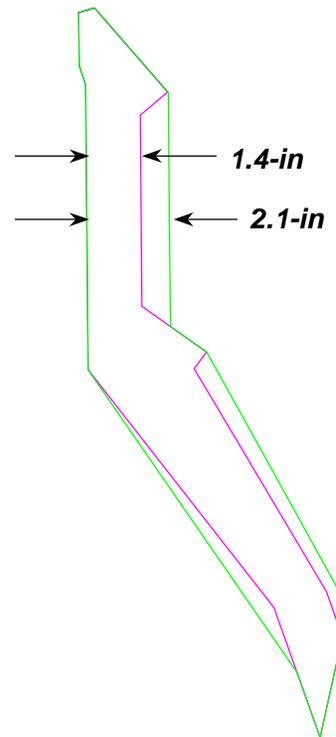
Changes to Improve Disruption Load Handling Capability

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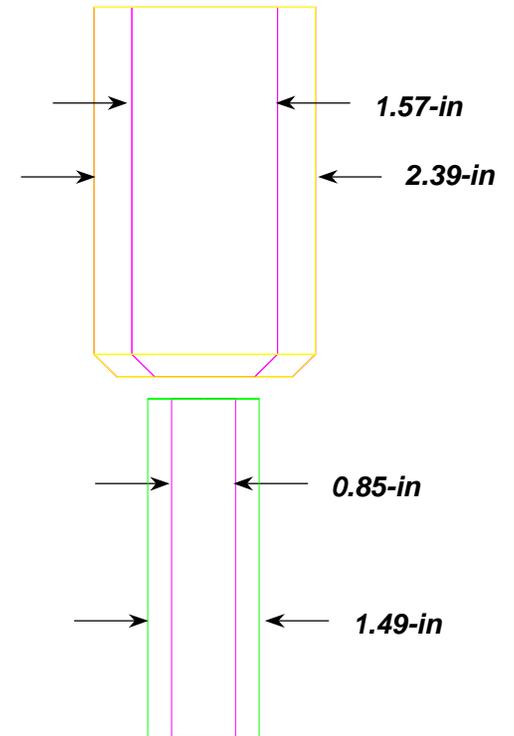
Lugs Enlarged, Single Vessel Support to Improve Load Distribution Tied Directly to Vessel Intershell Structure



Backplate Stiffened



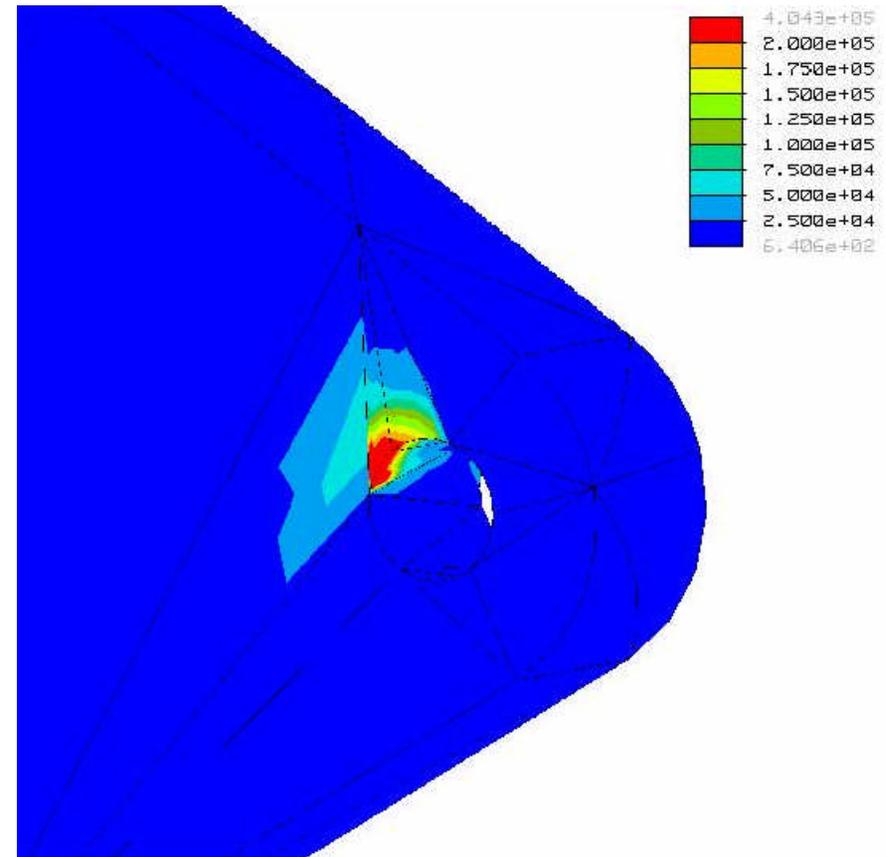
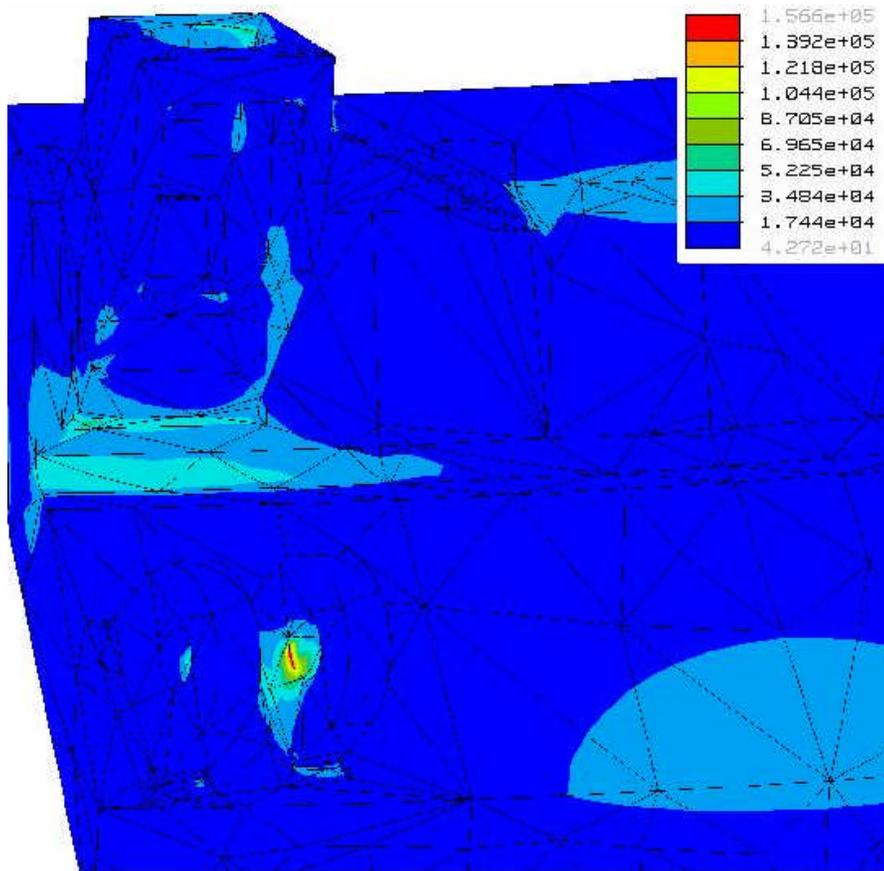
Pin Sizes Increased



Halo Current Results Summary

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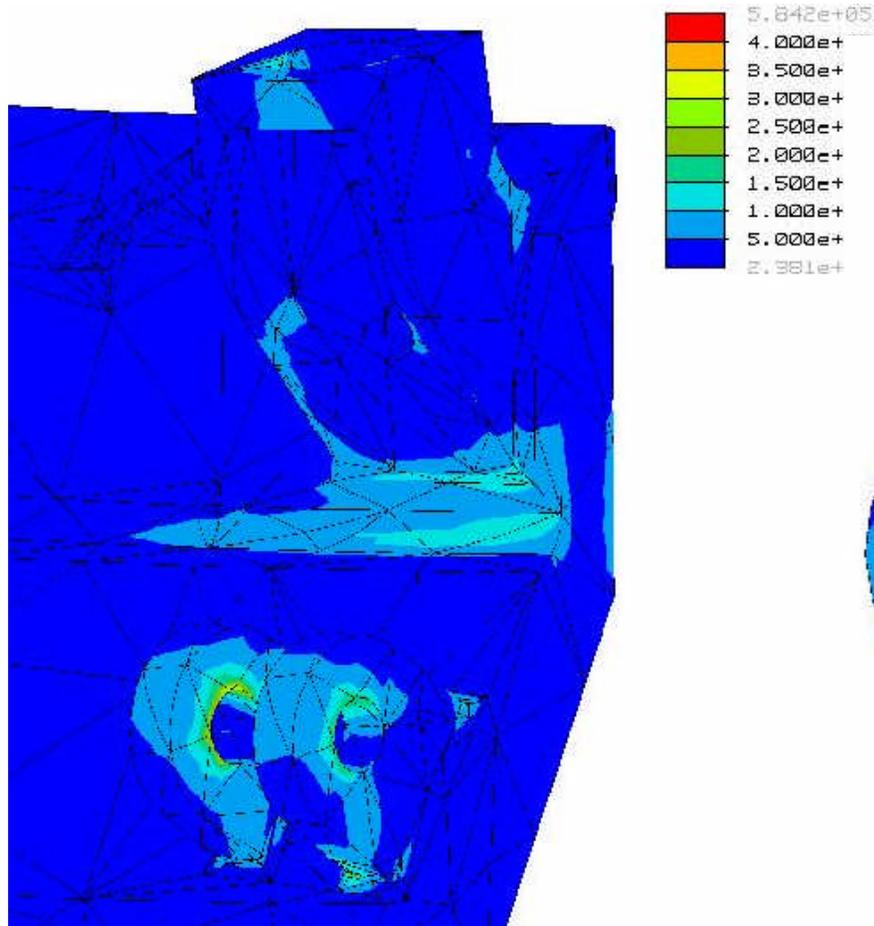
- ❑ Loads within 40 ksi allowable for SS316 in most areas
- ❑ Contact loads in lugs exceed bearing guideline of 1.5 yield



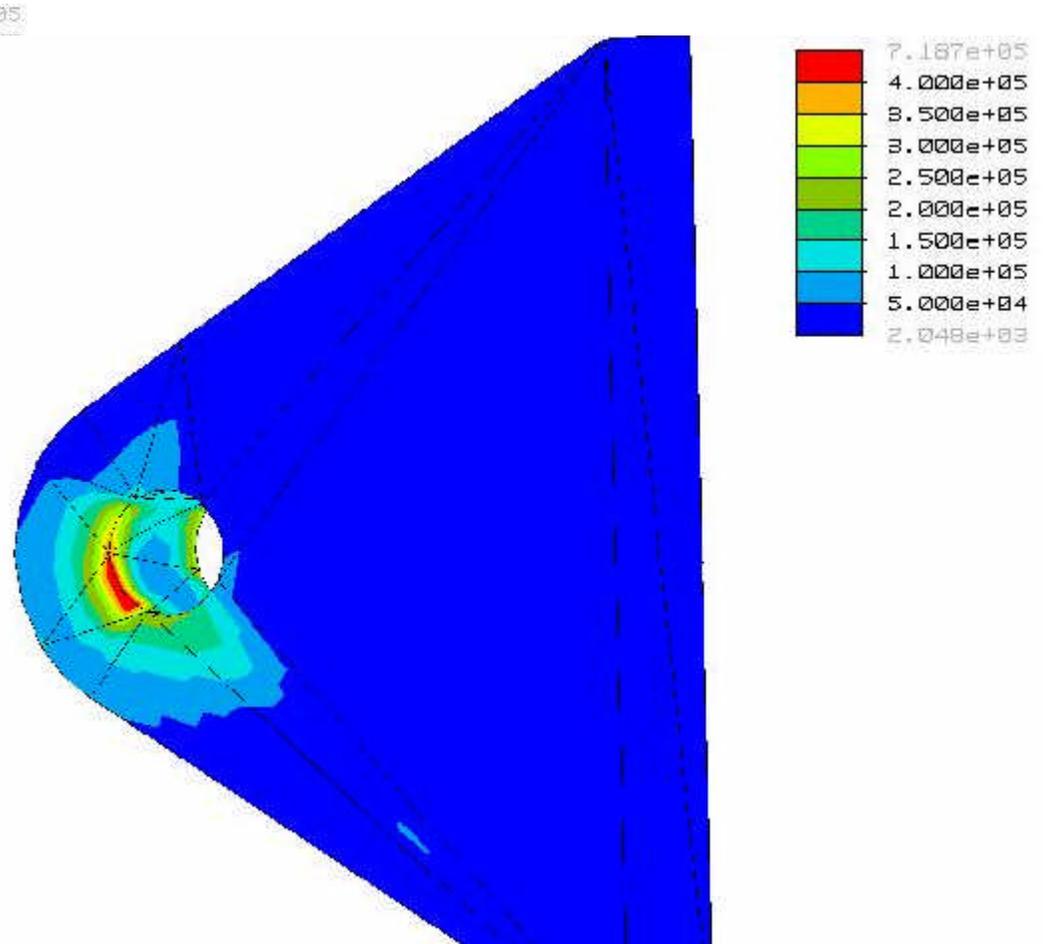
Disruption Eddy-Current Loads Require Inconel-718 Back Plate

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Backplate Loads Generally Below
150 ksi Yield for In-718



Some Plastic Deformation Expected Around
Vessel Support Holes (0.1-in Chamfer)



Finger Plate Pull-Off Assessment

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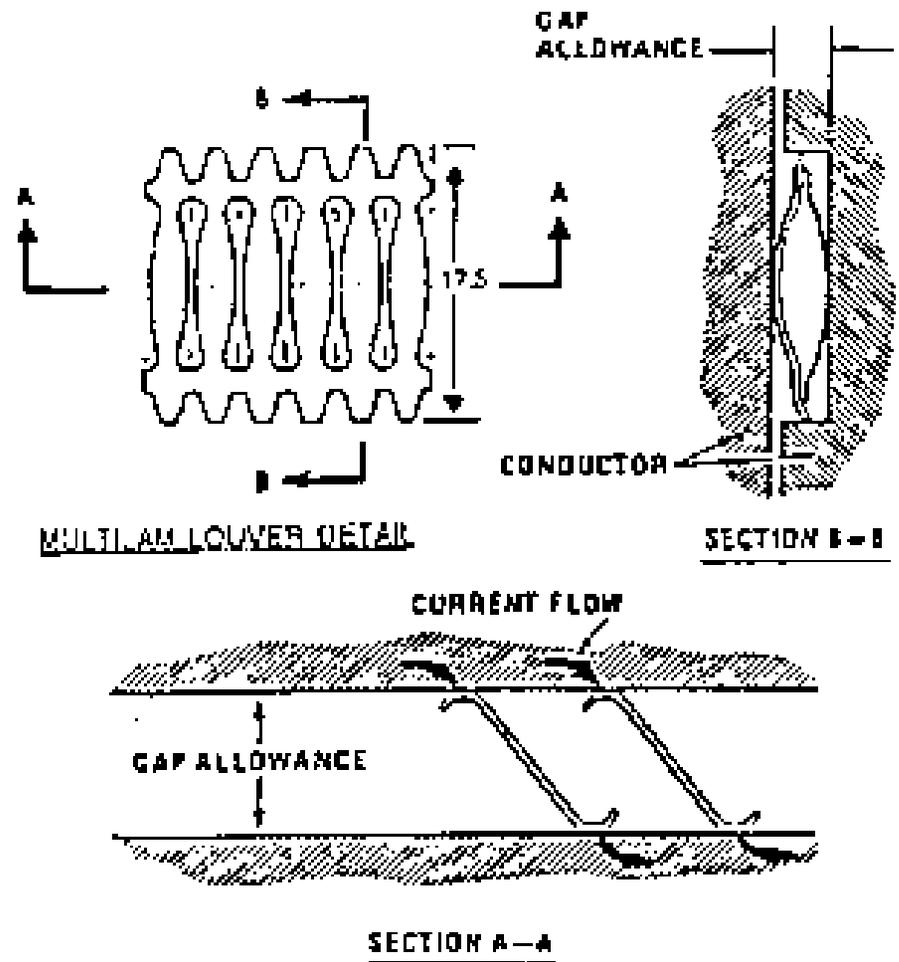
Is pin attachment scheme adequate if disruption eddy current flows primarily in outer two Cu-finger elements?

- Estimated load of 1.8 MN at each toroidal end of module, confined to 2 outer Cu-fingers**
- Must react 0.9 MN pull-off load through attachment pins on single finger**
- Requires minimum of 25 In-718 pins for baseline 4.5-mm diameter at backing plate interface**
- Requires 40 pin holes in CuCrZr for bearing load maximum of 90 ksi assuming load reacted over $\frac{1}{4}$ hole circumference**

Toroidal Electrical Connectors

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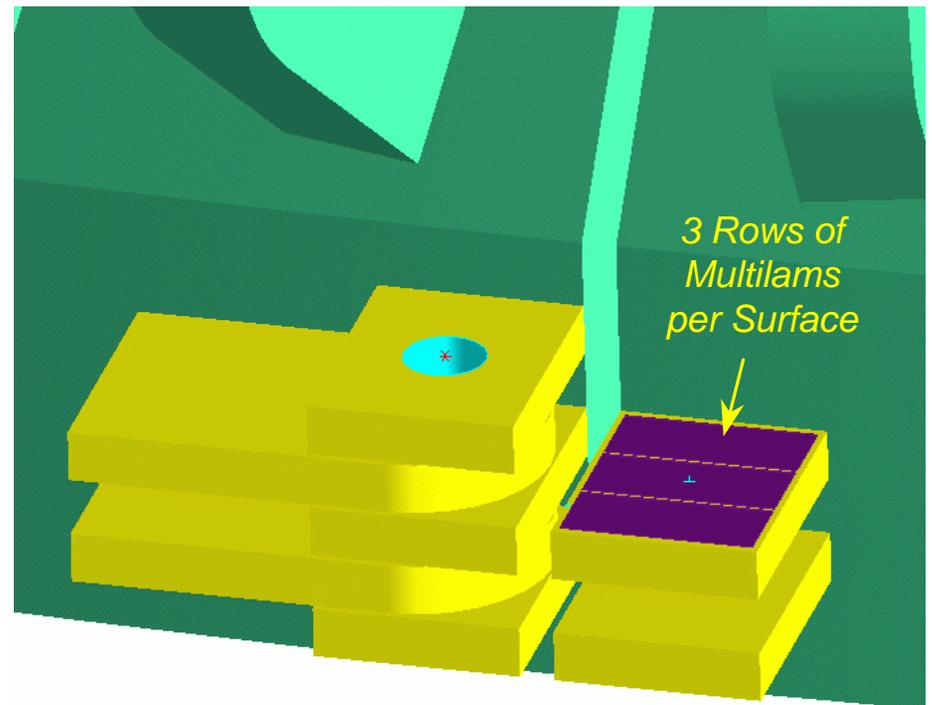
- ❑ Use Multilam® approach developed for ITER by General Atomics
- ❑ Assume type LAII/0.15 louver band with a width of 14-mm and a louver spacing of 1.5-mm
- ❑ Be-Cu material with good surface contact and spring capability
- ❑ Louvers will carry 750 A for a 1-sec duration short circuit condition with a surge capability (10-ms duration) of 3.5 kA
- ❑ Reference gap allowance is 0.5-mm for reliable contact force



Possible Connector Configuration

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- ❑ Estimated toroidal loop current of 400 kA during disruption
- ❑ Interweave louver strips to double contacts per unit length
- ❑ 56 cm² (8.7 in²) of area required to carry the 400 kA current
- ❑ Lugs retaining Multilam strips are 38-mm wide and contain 3 bands on each contact surface
- ❑ Rotating legs are ~82-mm long to bridge the gap between modules
- ❑ Plates are 10-mm thick to resist bending loads from the current flow



Remaining Issues for FY'01

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- ❑ **Assess/update outer divertor module design based on new disruption conditions (in-place, VDE, and radial disruption). Determine whether toroidal electrical connectors are required.**
- ❑ **Refine toroidal electrical connector concepts including alignment and remote handling requirements**
- ❑ **Develop conceptual design for actively-cooled baffle**
 - 2D & 3D thermal-structural analysis
 - Integration with vessel, primary cooling and remote handling systems
- ❑ **Update conceptual design for passively-cooled inner-divertor plate based on new disruption conditions**
 - 2D & 3D thermal-structural analysis
 - Integration with vessel and remote handling systems

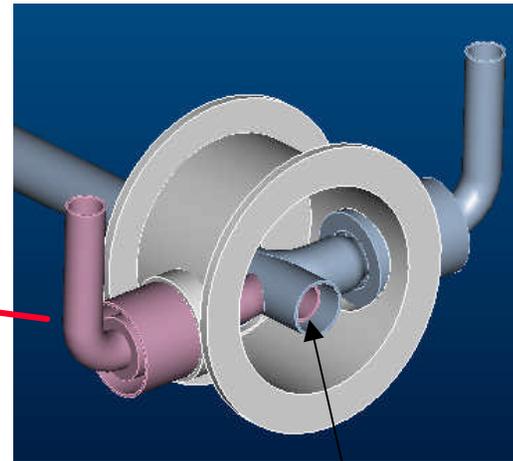
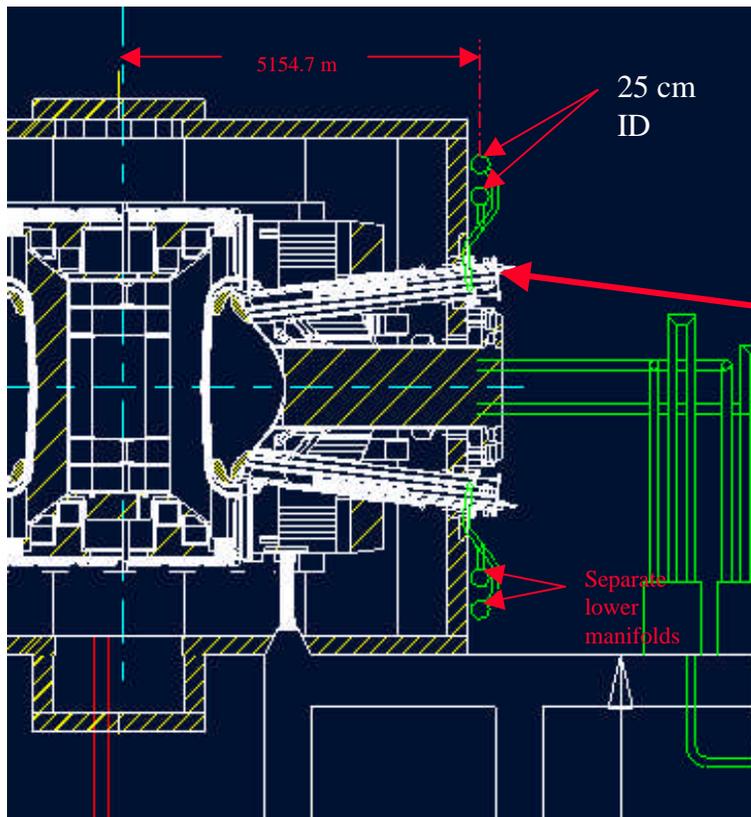
Required R&D Tasks to Confirm Design

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- Continue W-brush fabrication process development / scale-up and HHF testing to validate performance and improve reliability / manufacturability
- Continue outer divertor fabrication process development / scale-up begun under ITER through prototype development and testing
 - Channels combining heat transfer enhancement (helical wire, swirl tape, etc.) with W-brush armor
 - Cu-finger element integration with SS back structure (pins, welds, alignment, etc.)
- Continue baffle fabrication process development / scale-up
 - Large-area HIP-diffusion bonding
 - End manifold closeout welds
 - Large-area W-armor integration
- Development of effective passive heat transfer layer for first wall and inner divertor tiles (copper foam metals, etc.)
- Fabricate and test electrical connectors to validate performance and in-service design guidelines
- Fabricate dummy elements/end effectors to use for validating remote handling interfaces and procedures
- Continue Be plasma spray process development begun under ITER for the first wall armor application

Divertor Piping Concept

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80 mm ID inner pipe
120 mm ID outer pipe

Separate upper and lower manifolds supply lines feed a 90° quadrant of the machine assembly.

Tensile Tests Confirmed Bond Quality

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HIP joint properties slightly lower than base metal due to gas quench

